



Challenges in Imaging, Sensors, and Signal Processing

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MTO Technology Symposium

March 5 -7, 2007

Report Documentation Page				Form Approved OMB No. 0704-0188	
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1. REPORT DATE 05 MAR 2007		2. REPORT TYPE N/A		3. DATES COVERED -	
4. TITLE AND SUBTITLE Challenges in Imaging, Sensors, and Signal Processing				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) DARPA				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release, distribution unlimited					
13. SUPPLEMENTARY NOTES DARPA Microsystems Technology Symposium held in San Jose, California on March 5-7, 2007. Presentations, The original document contains color images.					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT UU	18. NUMBER OF PAGES 14	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified			



Outline

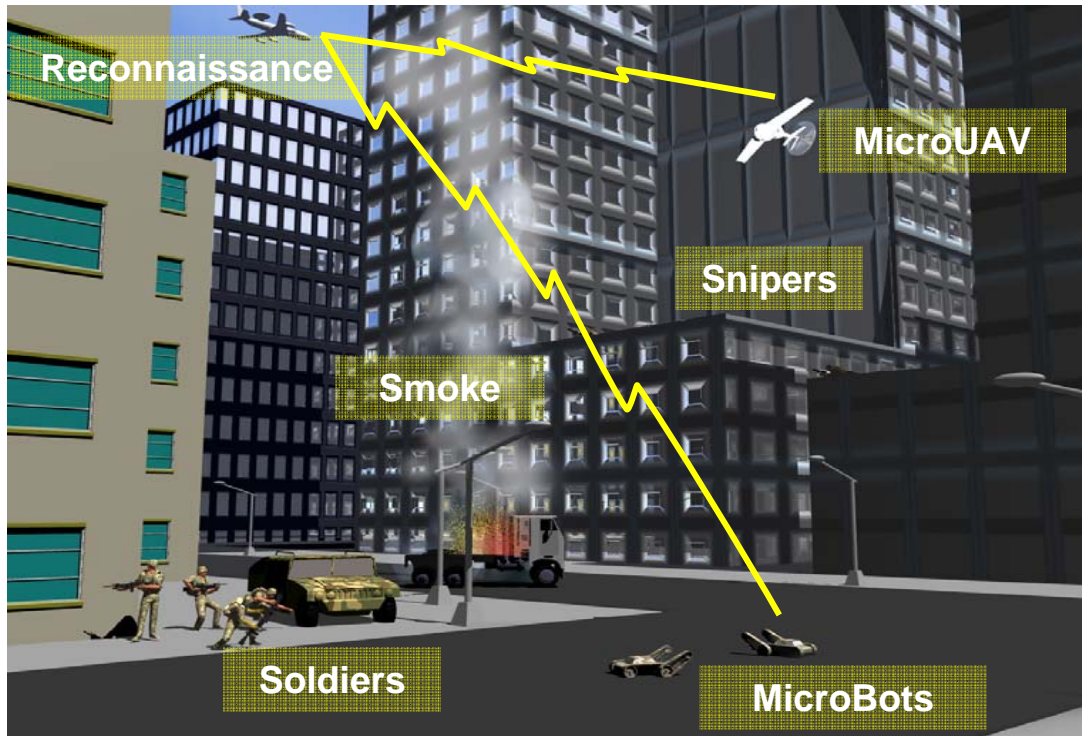


Challenges in Imaging, Sensors, and Signal Processing:

- The 3D FPA
- On-Focal Plane Processing
- Room Temperature Imaging
- Next Generation Multi-color & Adaptive Hyperspectral Sensors
- Sensor-on-a-Chip – Heterogeneous Material Integration
- Noiseless Imaging



Imaging & Sensing Technology Urban Scenario



Sensing technology for New Platforms:

- Next generation Micro-vehicles
 - ❖ Air and Ground
- Integrated sensing in multiple bands
- Operation in day / night
- Wide area persistent surveillance
- Information available on the ground
- Information available when needed
- Decisions-aids for critical information

Warfighter Will Have Inputs from Multiple Sources

Integration of these inputs into a common picture to provide:

- ❖ Threat location
- ❖ Situational awareness – friend and foe
- ❖ Assets available from other units / platforms
- ❖ Effect of operations

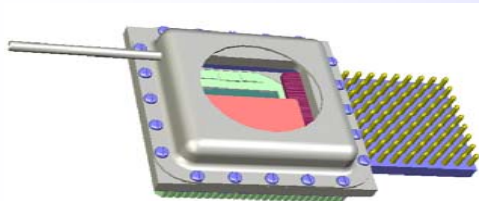


Imaging Micro-System Technology



Current Programs

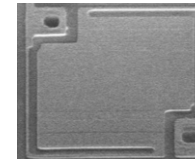
- New Thermal Structures
- Photon Detection



Integrated Multi-function Detector
with Integral Processing

- Spectrally Adaptive FPAs
- Two-Level 3-D Stack at the Detector

Room Temperature Imaging



Technology Enablers Bridging the Gap to New Capability

Integrated Multiple spectral bands

Decision making at the sensors

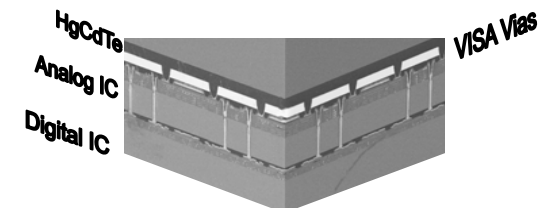
High density 3D Interconnections

Noiseless gain at the detector

New Capability

- Autonomous vehicles with intelligent sensing
- Sensors for micro/nano vehicles
- Panoramic multi-spectral
- Imaging in all-environments
- De-graded visibility imaging

3D Sensor Signal Processing

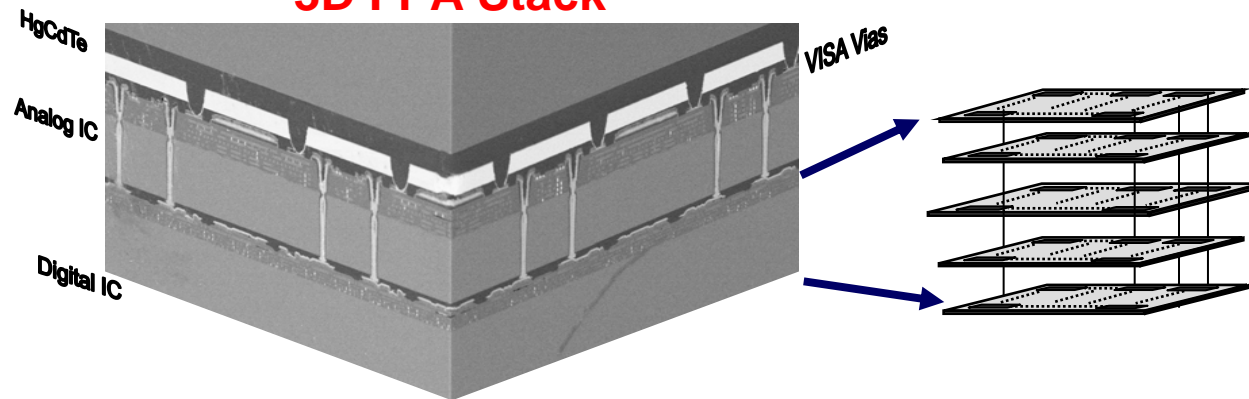




Three-Dimensional Infrared Focal Plane Array



3D FPA Stack



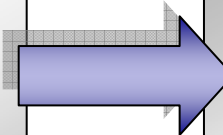
Combines Digital / Analog Technologies at the FPA

VISA Program will demonstrate signal processing at each pixel

Potential for Multi-level “Smart” FPA

Two-level Stack

- High Dynamic Range > 20 bits
- High Operating Temperature
- Increased Integration Time
- Higher Performance Two-Color Detectors



New Capabilities with Multi-level FPA

- Smart Spectral Processing
- FPAs adaptive to the environment
- On-chip Decision Making

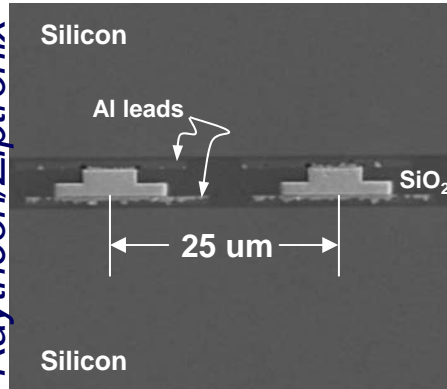


The Next Generation FPA Three-Dimensional Architecture



3D Silicon Read-out Integrated Circuits

Raytheon/Ziptronix



Direct Silicon Bonding

Results:

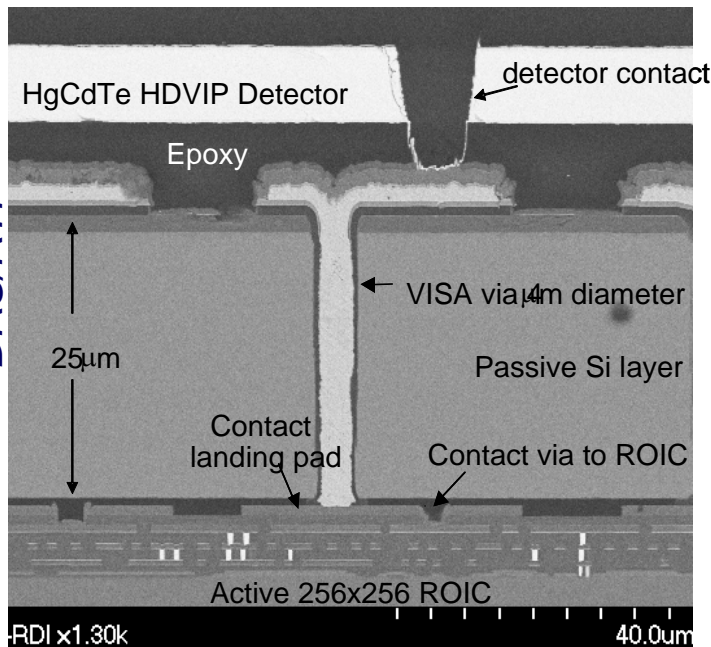
- 2 Layer Chain:
- 1 Silicon (7 μ m)
- 1 ROIC
- (10⁶ vias; 8 μ c-c)

99.998% Operability

The Next Challenges

- Higher Density Vias – < 1 μ m
- Multiple Wafer Stacks
- FPA 3D Architecture

DRS/RTI



Thin Epoxy Bond

Results:

- 2 Layer Stack:
- 1 Silicon (20 μ m)
- 1 ROIC
- (256x256; 30 μ c-c)

99.98% Operability

High interconnect operability Achieved between Silicon and FPA ROIC / Verified with Imaging from Analog Chip



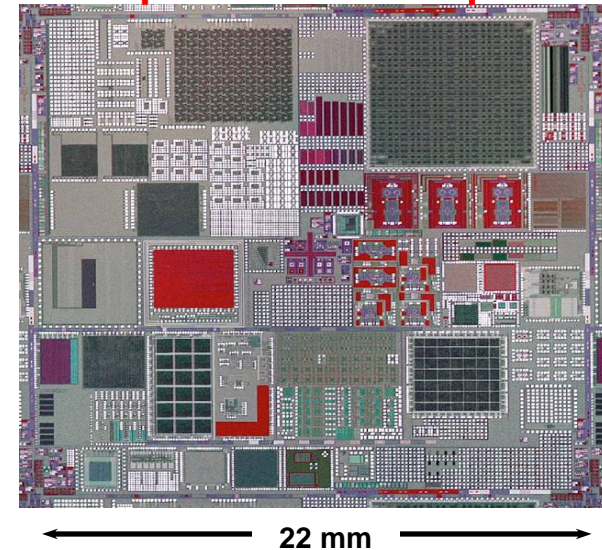
Three Dimensional Multi-Project Run Lincoln Laboratory



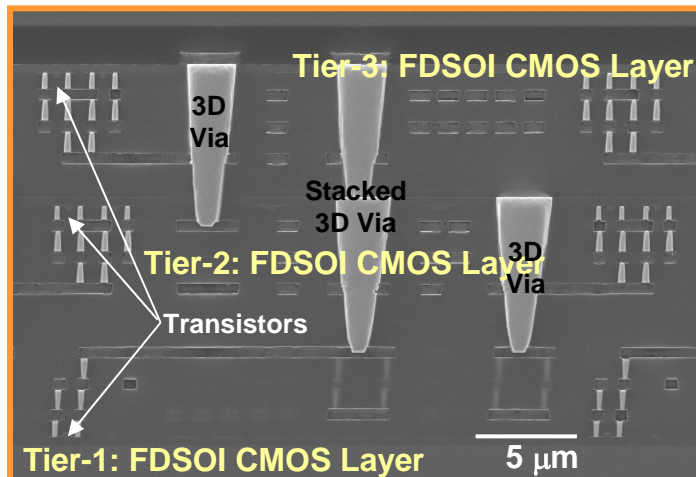
Wide Range of 3D Circuit Designs Completed in First Multi-project Run

3D FPGAs, digital, and digital/mixed-signal/RF
ASICs exploiting parallelism of 3D-interconnects
3D analog continuous-time processor
3D-integrated S-band digital beam former
Stacked memory (SRAM, Flash, and CAM)
Self-powered CMOS logic (scavenging)
Integrated 3D Nano-radio and RF tags
Intelligent 3D-interconnect evaluation circuits
DC and RF-coupled interconnect devices
Low Power Multi-gigabit 3D data links
Noise coupling/cross-talk test structures and circuits
Thermal 3D test structures and circuits

Completed 3DL1 die photo



3D Ring Oscillator Cross-Sectional



Three Level Silicon Stack using Silicon On Insulator (SOI)

- Functional 3-tier, 3D-integrated ring oscillator
 - Uses all three active transistor layers, 10 levels of metal and experimental stacked 3D-vias
 - Demonstrates viability of 3D integration process



Advanced Imaging Applications Large Continuous Data Streams



From ChartTiff Urban Area Aerials



Imaging Arrays for
Large Area Surveillance

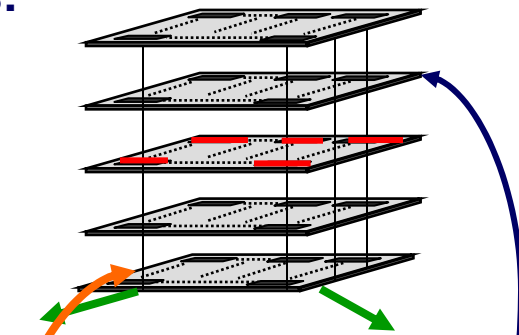


Detail on Demand



Day Night
Persistent Surveillance

Issues:

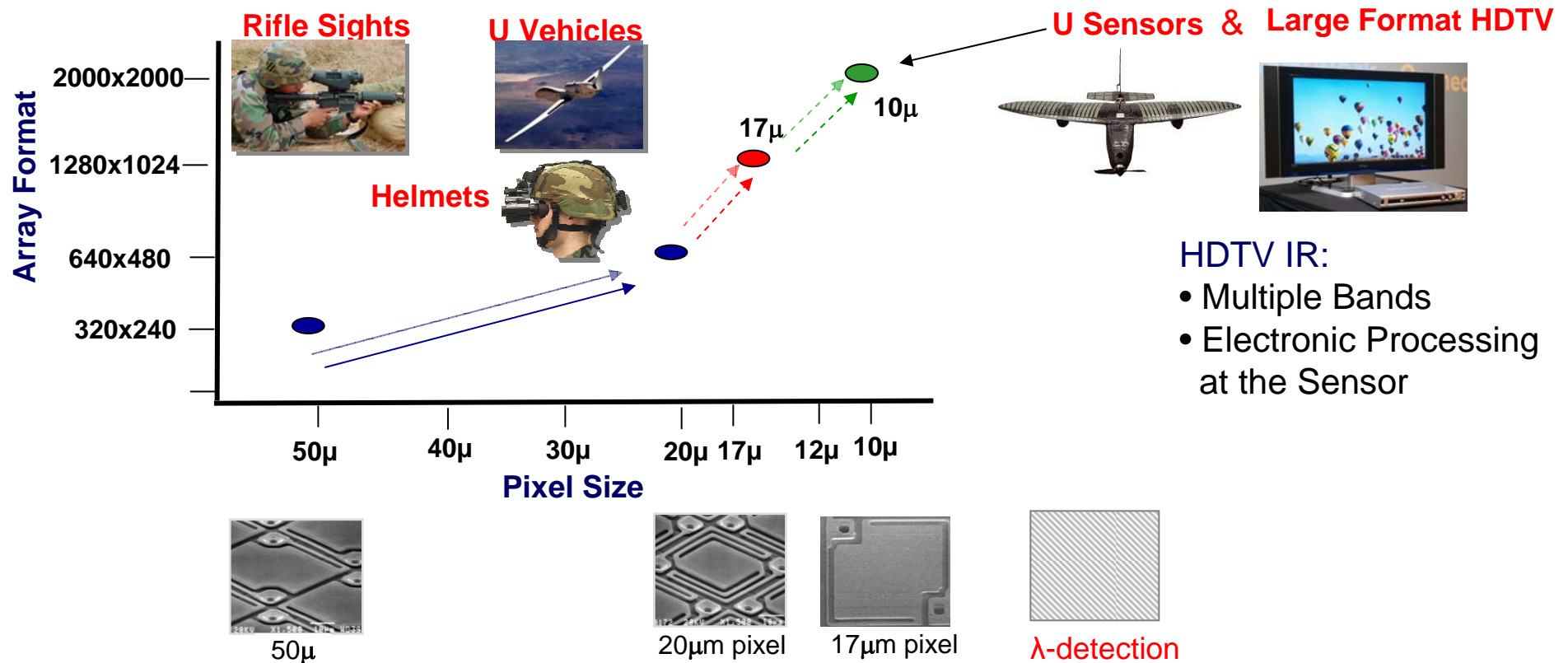


Sensor Pre-Processing

- Change Detection
- Feature / Edge Extraction
- Adaptive Spatial Filters
- Preliminary Decision Making
- Thermal Management / Heat Extraction



Room Temperature Infrared

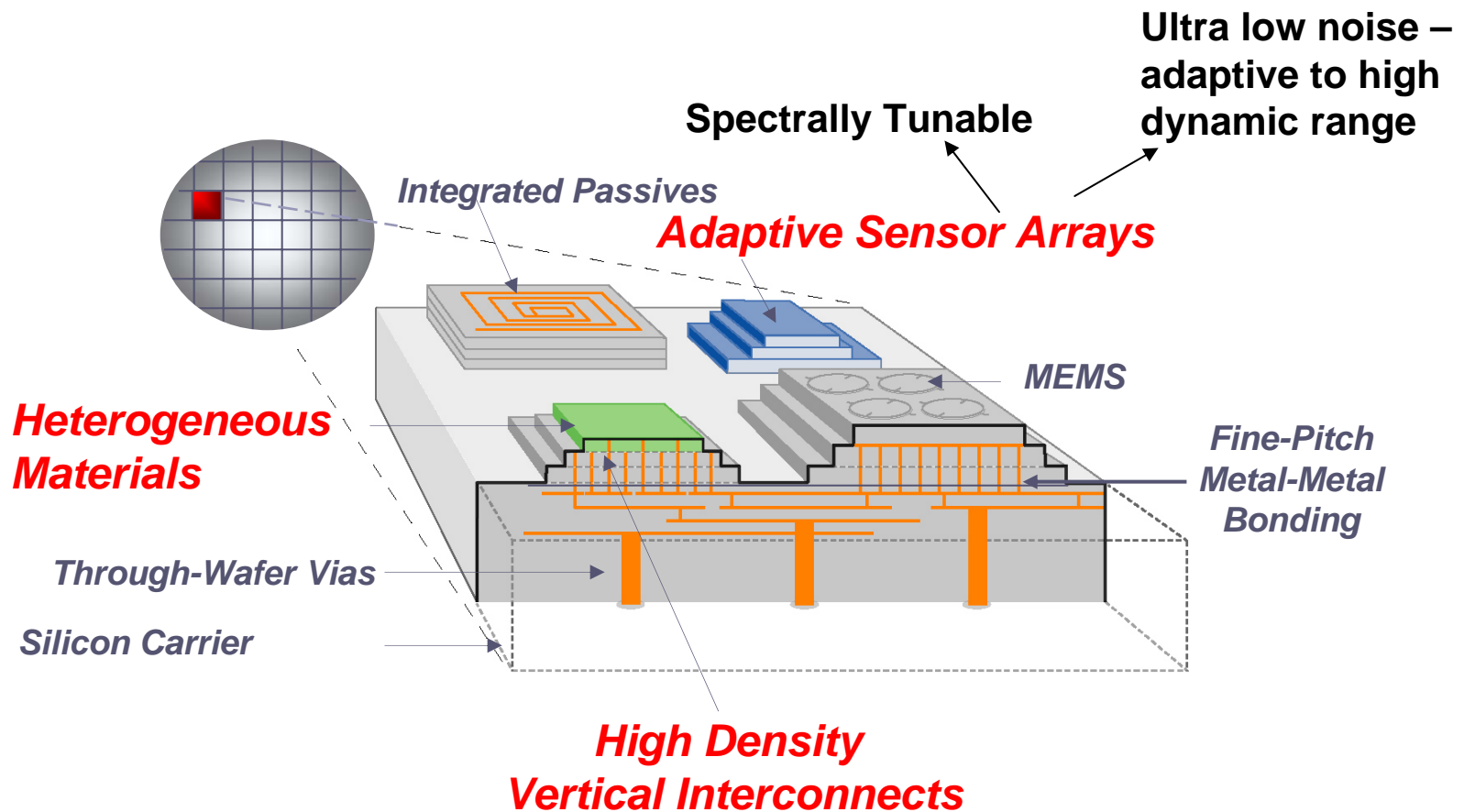


High Density Array Formats Lead to New Capabilities:

- Micro Sensors- Reduced Weight, Smaller Optics, Size & Volume
- High Definition Arrays
- Increased Range



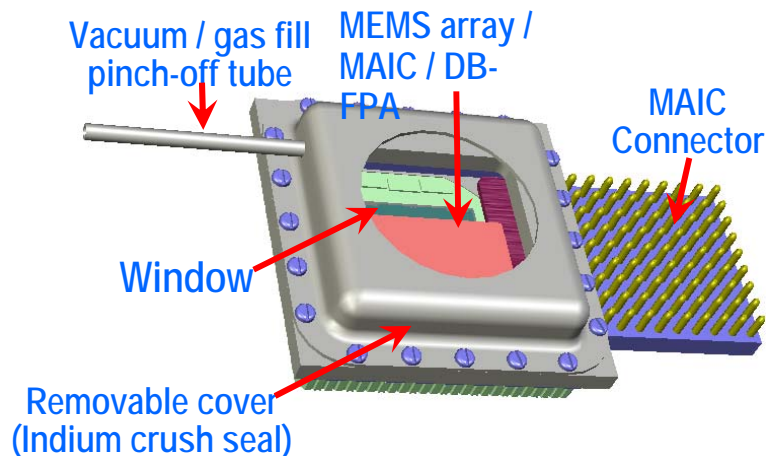
Sensor on a Chip Concept



Adapted from Sensor Integration
Concept RTI / DRS IR Technologies



Spectrally Adaptive Focal Plane Array



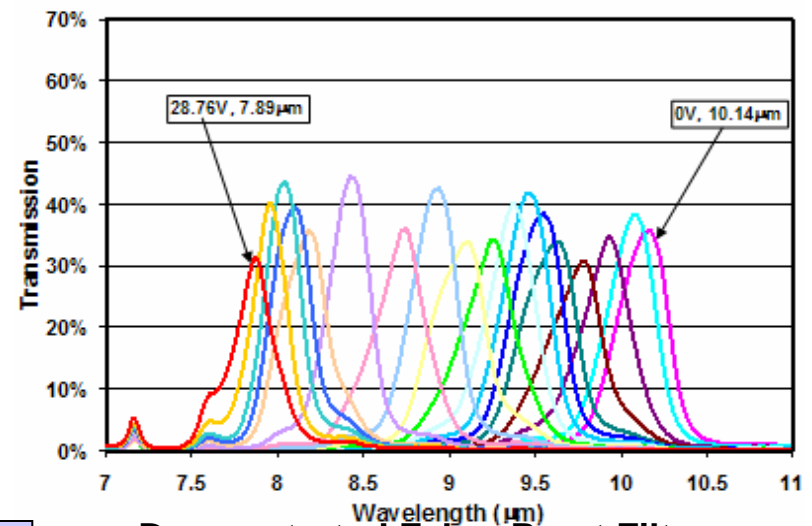
Prototype Integrated Tunable FPA Planned in FY 07

- Future tunable FPAs will:
- Adapt to the environment
- Autonomously detect anomalies
- Select spectral band to optimize contrast
- Analyze scene content
- New Ideas ?

Low Contrast LWIR

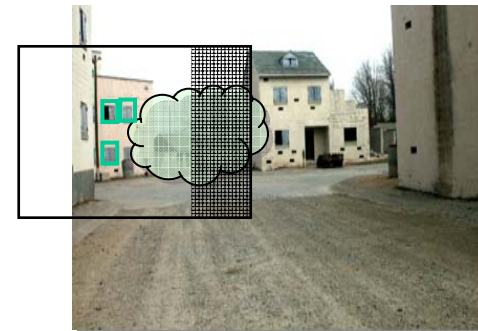


Camouflage SWIR



Demonstrated Fabry Perot Filters
Tunable from 8 – 10 μm

Chemical Detection





Noiseless Room Temperature FPA



Raytheon

State of the Art SWIR Camera
Input Noise 40 – 50 e⁻



High Gain Input Circuit
Input Noise ~ 10 e⁻



- 1280 x 1024; 20 μm pixels
- Short Integration 1.8 msec.
- F/13 Optics
- Temperature -18 C

Goodrich – Sensors Unlimited

State of the Art SWIR Camera
Input Noise 40 – 50 e⁻



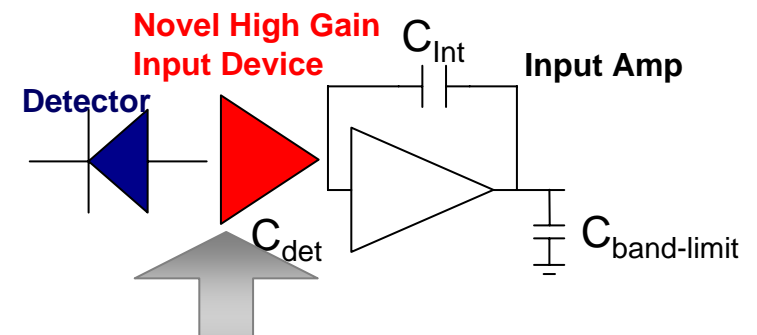
High Gain Input Circuit
Input Noise ~ 10 e⁻



- 480 x 512; 20 μm pixels
- Integration Time: 16 msec
- F/2.8 Optics
- Temperature +18°C

Demonstration of Low Read-out Noise SWIR

Improvements in Imaging with Low Noise
Input SWIR 20 μm unit cell



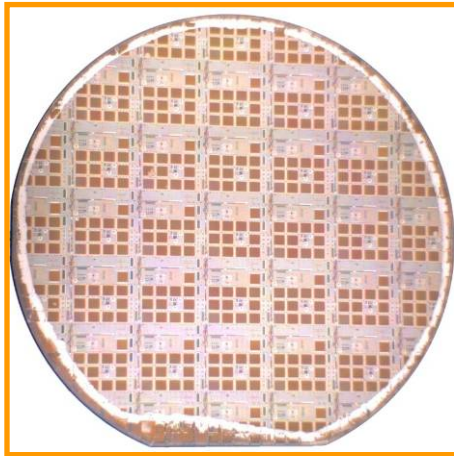
High Gain / Low (zero) Excess Noise
Uniformity in Large Arrays
Unit cell $\sim \lambda$
High Dynamic Range
Adaptable to high Illumination



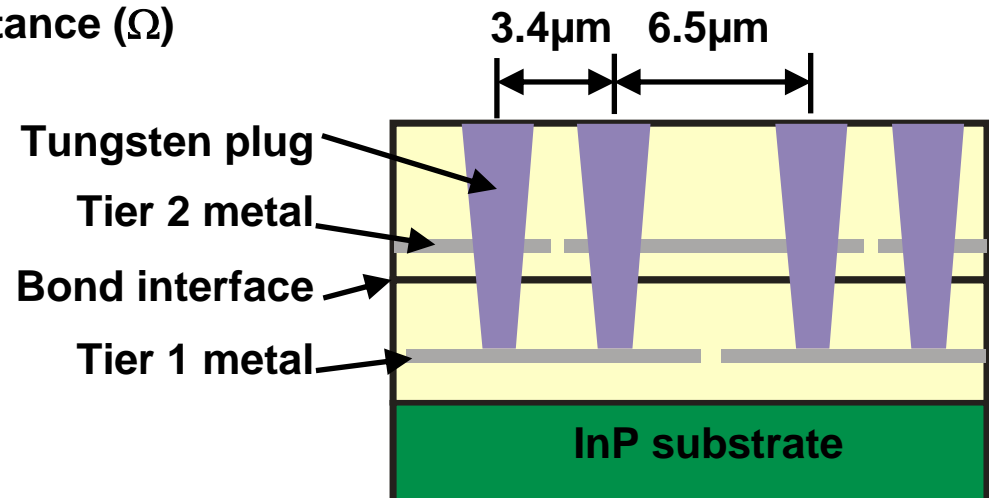
Wafer Bonding Heterogeneous Materials



Wafer Die Map of Average 3D-Via Resistance (Ω)
for 10,000-via Chains < 1 ohm



Photograph of 150-mm InP Wafer
with Aligned and Bonded Tier



Lincoln Laboratory:

First Steps toward Heterogeneous
Integration of Imaging Materials

Wafer Level Integration Photonic Materials with Silicon:

- Narrow band detectors integrated with state of the art CMOS processing
- Extremely large arrays – potentially wafer level
- Higher density, smaller size pixels



Summary

- **Three dimensional FPAs and signal processors provide the basis for future imaging technology**
- **First steps taken through development of high operability interconnections, new ideas needed for:**
 - ❖ High density vias
 - ❖ Architecture
 - ❖ Heat extraction
- **Room temperature imaging has advanced significantly, but future advances needed in:**
 - ❖ Single electron noise
 - ❖ Broad-band Imaging
- **Demonstration of hyper / multi-spectral imaging at the sensor provides first steps toward FPAs that interaction / adapt to the environment**
- **Sensor system-on-a-chip concepts bring together information from multiple sensor modes**